	SIPA	
B/O FORM PTO Patent and Traden	, ,	U.S. Departr
RECORDATION	FORM COVER SHEET / IIII 0 8 2002	<u>ဂ္ဂ</u> ်) 102494312
PATENTS ONLY	03	HITA.0344
To do Hananda	Commissioner of Potents and	asse record the attached original documents or conv thereof
To the Honorable Commissioner of Patents and Commissioner		
1. Name of Con	veying Party(ies):	2. Name and Address of Receiving Party(ies):
(3) Kaname	ANETANI, (2) Hiroaki NAMBU, YAMASAKI, (4) Fumihiko ., (5)Takeshi KUSUNOKI and IIGETA	Name: Hitachi, Ltd. Address: 6, Kanda Surugadai 4-chome City: Chiyoda-ku, Tokyo, Japan and
Additional names of 3. Nature of Co.	f conveying parties attached:  Yes  No onveyance:	(2) Name: Hitachi Device Engineering Co Ltd Address: 3682, Hayano, Mobara-shi Chiba-ken, Japan 297-8581
	ment	
Execution Da	tte: (1) (2) December 3, 2001 (3) 001 and (4)(5)(6) December 4, 2001	
4. (a) Patent A	pplication Number(s):	
	10/360,867	4. (b) Patent Numbers:
If this document the execution dat	is being filed together with a new application, the of the application is:  umbers Attached.	
5. Name and A Concerning this I	Address of Party to whom Correspondence Document Should be Mailed:	6. Total Number of Applications and Patents Involved: 1
Name:	Stanley P. Fisher	7. Total Fee: \$40.00 (37 C.F.R. § 3.41)
Address:	Reed Smith LLP 3110 Fairview Park Dr. Suite 1400 Falls Church, VA. 22042	<ul><li>☑ Enclosed.</li><li>☑ Authorized to be charged to deposit account.</li></ul>
		8. Deposit Account Number: 08-1480
		ATTACH DUPLICATE COPY OF THIS PAGE IF PAYING BY DEPOSIT ACCOUNT
DO NOT USE T	THIS SPACE	
9. Statement	and Signature:	
original docume	nt.	July 8, 2003  Juan Carlos A Marquez, Registration No. 34,072
Total number of pages comprising cover sheet: 1		

07/10/2003 ECOOPER 00000102 10360867

01 FC:8021

40.00 OP

PATENT REEL: 014249 FRAME: 0553 B/O FORM PTO 1595 (1/31/92) Patent and Trademark Office RECORDATION FORM COVER SHEET PATENTS ONLY



HITA.0344

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof. 02.10.03 2. Name and Address of Receiving Party(ies): 1. Name of Conveying Party(ies): (1) Kazuo KANETANI, (2) Hiroaki (1) Name: Hitachi, Ltd. NAMBU, (3) Kaname YAMASAKI, (4) Address: 6, Kanda Surugadai 4-chome Fumihiko ARAKAWA, (5) Takeshi Chiyoda-ku, Tokyo, Japan KUSUNOKI and (6) Keiichi HIGETA and Additional names of conveying parties attached: ☐ Yes ☐ No (2) Name: Hitachi Device Engineering Co.. Ltd Address: 3681, Hayano, Mobara-shi Nature of Conveyance: Chiba-ken, Japan 297-8581 Assignment Merger Change of Name Security Agreement Other: Execution Dates: (1)(2) Dec. 3, 2001; (3) Dec. 6, 0360867 2001; and (4)(5)(6) Dec. 4, 2001 (a) Patent Application Number(s): (b) Patent Numbers: If this document is being filed together with a new application, the execution dates of the application are: Additional Numbers Attached. 5. Name and Address of Party to whom Correspondence Total Number of Applications and Patents Involved: 1 Concerning this Document Should be Mailed: Stanley P. Fisher Name: \$40.00 Total Fee: (37 C.F.R. § 3.41) Reed Smith LLP Address: Enclosed. 3110 Fairview Park Dr. Authorized to be charged to deposit account. Suite 1400 Falls Church, Va. 22042 Deposit Account Number: 08-1480 ATTACH DUPLICATE COPY OF THIS PAGE IF PAYING BY DEPOSIT ACCOUNT DO NOT USE THIS SPACE Statement and Signature: To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document. Stanley P. Fisher, Registration No. 24, 344 istration No. 34,072 Total number of pages comprising cover sheet

02/12/2003 HMARZII 00000015 10360867

02 FC:8021

40-00 ND

PATENT REEL: 014249 FRAME: 0554

## ASSIGNMENT

(譲渡証)

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to the below named inventor(s), citizens of Japan by HITACHI, LTD., and Hitachi Device Engineering Co., Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 3682, Hayano, Mobara-shi, Chiba, Japan, respectively, receipt of which is hereby acknowledged, we, the below named inventor(s), do hereby sell and assign to said HITACHI, LTD., and Hitachi Device Engineering Co., Ltd., their successors and assigns, all our right, title and interest, in and for the United States of America, in and to

## SEMICONDUCTOR INTEGRATED CIRCUIT

invented by us and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., and Hitachi Device Engineering Co., Ltd., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made;

And we hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And we do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD., and Hitachi Device Engineering Co., Ltd.

Signed on the date(s) indicated aside our signatures:

RECORDED: 07/08/2003

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) Kazuo Kanatani	12/3/2001
2) Hiroaki Namby	12/3/2001
3) Kaname Yamasaki	12/6/2001
4) Fumihiko Arakawa	12/4/2001
5) Takeshi Kusunoki	12/4/2001
6) Kecichi Higeta	12/4/2001
7)	
8)	
9)	
(0)	

PATENT REEL: 014249 FRAME: 0555